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Part Number: [0738020017](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Midplane Header, Vertical, SMC, Press-Fit, Long Pin, Guide Pin Option, Guide Post Location A, Polarizing Key Position N/A, 72 Circuits

Documents:

3D Model	Packaging Specification PK-70873-0868 (PDF)
Drawing (PDF)	Test Summary TS-73670-990-001 (PDF)
Product Specification PS-73780-999-001 (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E29179

General

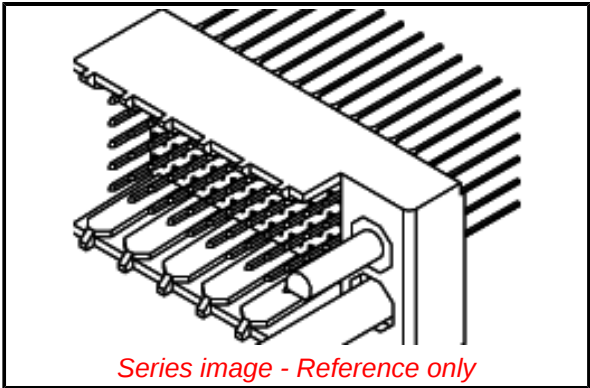
Product Family	Backplane Connectors
Series	73802
Application	Midplane
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754834667

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	Yes
Material - Metal	Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	7.55mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	3.95mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55° to +105°C

Electrical

Current - Maximum per Contact	1.0A
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Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Not Relevant

China RoHS

REACH SVHC

Not Relevant

Halogen-Free

Status

Not Relevant

For more information, please visit [Contact US](#)

China ROHS	Not Relevant
ELV	Not Relevant
RoHS Phthalates	Not Relevant

Search Parts in this Series

[73802](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard Receptacle. [73780](#) HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
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Backplane Signal Insertion Module	622008502
Press-In Tool for 2.00mm Pitch HDM* Board-to-Board Backplane Header	

Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0868
Product Specification	PS-73780-999-001
Sales Drawing	SD-73802-001
Test Summary	TS-73670-990-001

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